ABSTRACT

BALL GRID ARRAY TYPE PACKAGE FOR SEMICONDUCTOR DEVICE

A semiconductor device with a BGA package includes a substrate (12) made of a resin and having one side on which a number of solder ball terminals (13) are formed and the other side on which a chip mounting portion electrically connected to the solder ball terminals (13) is formed, and a cover plate (16) made of a metal and attached to a semiconductor chip (14) so as to cover and come into contact with it under a condition where the semiconductor chip (14) is connected to the resin substrate (12) by a flip-chip process. The cover plate (16) includes a peripheral portion formed with a plurality of bonding portions (16c) where the cover plate (16) is bonded to the substrate (12). The bonding portions (16c) are discontinuous to each other.

FIGURE 1A